

	Hits	Search Text	DBs
38	2	((substrate or wafer or platen) same (control\$4 or regulat\$4 or (mass\$4 near9 flow\$4 near9 control\$4) or flowmeter) same (distribut\$4 or spray\$4 or nozzle) same develop\$4 same (resist or photoresist or photosensitive)) and (dissolv\$4 or solubiliz\$4) and ((heat\$4 or bak\$4 or thermal\$4) same (resist or photoresist)) and (heat\$4 same (top or upper) same (bottom or lower or (sustrate near5 holder) or hold\$4 or stage) same (resist or photoresist) same (substrate or wafer) same pressure)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
39	4	((substrate or wafer or platen) same (control\$4 or regulat\$4 or (mass\$4 near9 flow\$4 near9 control\$4) or flowmeter) same (distribut\$4 or spray\$4 or nozzle) same develop\$4 same (resist or photoresist or photosensitive)) and (heat\$4 same (top or upper) same (bottom or lower or (sustrate near5 holder) or hold\$4 or stage) same (resist or photoresist) same (substrate or wafer) same pressure) and develop\$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
40	260	((heat\$4 or anneal\$4 or bak\$4) same (top or upper or front) same (bottom or lower or (substrate near5 holder) or hold\$4 or stage) same (resist or photoresist) same (substrate or wafer) same pressure) and develop\$4 and ((coat\$4 or form\$4) same (resist or photoresist)) and (exposure or irradiat\$4))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
41	323	((heat\$4 or anneal\$4 or bak\$4) same (top or upper or front) same (bottom or lower or (substrate near5 holder) or hold\$4 or stage) same (resist or photoresist) same (substrate or wafer) same pressure) and develop\$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
42	55	((top or upper or front) same (bottom or lower or (substrate near5 holder) or hold\$4 or stage) same (resist or photoresist) same (substrate or wafer) same (pressure or Torr or pascal or "Pa")) and ((resist or photoresist) near36 develop\$4) and ((heat\$4 or bak\$4 or anneal\$4 or PEB or (post near9 bak\$4)) same (substrate or wafer or workpiece) same (photoresist or resist or photocur\$4 or polyimide) same pressure same control\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB